

ABSTRACT

A heat dissipation module for CPU has a heat dissipation device, a fan-fixing frame and a fan. The fan-fixing frame is located on the heat dissipation device and has a top plate, four posts and a plurality of elastic pressing components. The posts extend downwardly from four corners of the top plate. The posts each have a clipping element at a bottom thereof. The elastic pressing components are installed on the top plate. The fan is fixed on the top plate of the fan-fixing frame. The fan-fixing frame is disposed on the retention frame. The clipping elements at the bottoms of the posts of the fan-fixing frame respectively clip clipping holes at four supporting protrusions of the retention frame. The elastic pressing components thereby elastically press the heat dissipation device to abut against a heat-exhausting surface of the CPU.